Innovative packaging for China's smartphone market

The Associated Press

STATS ChipPAC Ltd. ("STATS ChipPAC") (SGX-ST: STATSChP) (SGX: S24) today announced implementation of breakthrough performance and packaging innovation in multiple advanced chipsets for the rapidly developing smartphone market in China. Spreadtrum Communications, a leading fabless semiconductor provider in China, has adopted STATS ChipPAC's packaging innovations for a number of its mobile chipsets. The combination of Spreadtrum's advanced silicon design capabilities with STATS ChipPAC's next generation embedded Wafer Level Ball Grid Array (eWLB) packaging technology offers increased performance and compact form factor at a competitive cost for the fast-growing China smartphone market.

Spreadtrum offers mobile chipsets for a range of smartphones, feature phones and other consumer electronics products that support 2G, 3G and 4G wireless communications standards. Spreadtrum's TD-SCDMA (time division synchronous code division multiple access) chipsets have set a new standard for increased performance and size reduction in the highly competitive smartphone market in China. TD-SCDMA is a 3G mobile telecommunications standard that is currently utilized in China to enable data, voice, video and media in mobile phones and internet-enabled devices.

"China is now the single largest smartphone market in the world and is rapidly growing," said Brian Chen, Vice President of Operations at Spreadtrum. "By combining our unique chip architecture and leading TD-SCDMA modem technology with STATS ChipPAC's technology and manufacturing leadership, we have been able to deliver high performance TD-SCDMA chipsets in a package format that continues to provide Spreadtrum and our customers with a clear competitive advantage in the China market."

eWLB is a powerful fan-out wafer level packaging (FOWLP) technology and integration platform that provides significant advantages including a more space-efficient package design enabling a smaller footprint, higher density input/output (IO) and a lower package height than is possible with laminate or flip chip semiconductor packages. Spreadtrum and STATS ChipPAC are jointly working to utilize innovative packaging technology across a full spectrum of complex product designs such as dual and quad core mobile processors.

"Our extensive collaboration with Spreadtrum demonstrates the transformative advantages of eWLB technology. We have been able to rapidly optimize the overall functional performance of their silicon with an innovative packaging technology designed to optimize speed, performance and size at an overall lower cost of ownership," said Dr. Han Byung Joon, Executive Vice President and Chief Technology Officer, STATS ChipPAC. "Spreadtrum's success in China and beyond is

evident by the numerous product introductions and global customer wins they have had and we are excited to be working together to drive innovations in the smartphone market."

Forward-Looking Statements
Certain statements in this release are forward-looking statements that involve a number of risks and uncertainties that could cause actual results to differ materially from those described in this release. Factors that could cause final actual results to differ include, but are not limited to, the amount of the business interruption insurance claim due to flooding of the Thailand Plant; the ability to shift production to other manufacturing locations, shortages in supply of key components and disruption in supply chain; general business and economic conditions and the state of the semiconductor industry; prevailing market conditions; demand for end-use applications products such as communications equipment, consumer and multi-applications and personal computers; decisions by customers to discontinue outsourcing of test and packaging services; level of competition; our reliance on a small group of principal customers; our continued success in technological innovations; pricing pressures, including declines in average selling prices; intellectual property rights disputes and litigation; our ability to control operating expenses; our substantial level of indebtedness and access to credit markets; potential impairment charges; availability of financing; changes in our product mix; our capacity utilisation; delays in acquiring or installing new equipment; limitations imposed by our financing arrangements which may limit our ability to maintain and grow our business; returns from research and development investments; changes in customer order patterns; customer credit risks; disruption of our operations; loss of key management or other personnel; defects or malfunctions in our testing equipment or packages; rescheduling or cancelling of customer orders; adverse tax and other financial consequences if the taxing authorities do not agree with our interpretation of the applicable tax laws; classification of our Company as a passive foreign investment company; our ability to develop and protect our intellectual property; changes in environmental laws and regulations; exchange rate fluctuations; regulatory approvals for further investments in our subsidiaries; majority ownership by Temasek Holdings (Private) Limited ("Temasek") that may result in conflicting interests with Temasek and our affiliates; unsuccessful acquisitions and investments in other companies and businesses; labour union problems in South Korea; uncertainties of conducting business in China and changes in laws, currency policy and political instability in other countries in Asia; natural calamities and disasters, including outbreaks of epidemics and communicable diseases; the continued trading and listing of our ordinary shares on the Singapore Exchange Securities Trading Limited ("SGX-ST"). You should not unduly rely on such statements. We do not intend, and do not assume any obligation, to update any forward-looking statements to reflect subsequent events or circumstances.

About STATS ChipPAC Ltd.
STATS ChipPAC Ltd. is a leading service provider of semiconductor packaging design, assembly, test and distribution solutions in diverse end market applications including communications, digital consumer and computing. With global headquarters in Singapore, STATS ChipPAC has design, research and development,

manufacturing or customer support offices throughout Asia, the United States and Europe. STATS ChipPAC is listed on the SGX-ST. Further information is available at www.statschippac.com [1]. Information contained in this website does not constitute a part of this release.

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